

**SN74BCT757**  
**OCTAL BUFFER/DRIVER**  
**WITH OPEN-COLLECTOR OUTPUTS**  
 SCBS041D – NOVEMBER 1989 – REVISED NOVEMBER 1993

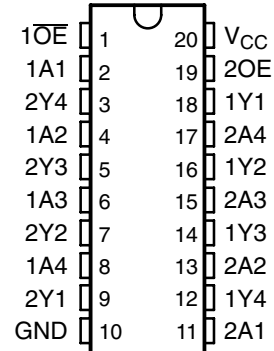
- BiCMOS Design Significantly Reduces  $I_{CCZ}$
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model ( $C = 200$  pF,  $R = 0$ )
- Open-Collector Outputs Drive Bus Lines or Buffer Memory Address Registers
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic 300-mil DIPs (N)

## description

This octal buffer and line driver is designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. This device provides complementary output-enable ( $OE$  and  $\overline{OE}$ ) inputs and noninverting outputs.

The SN74BCT757 is characterized for operation from 0°C to 70°C.

**DW OR N PACKAGE  
(TOP VIEW)**



**FUNCTION TABLES**

INPUTS		OUTPUT
$\overline{1OE}$	1A	1Y
H	X	H
L	L	L
L	H	H

INPUTS		OUTPUT
2OE	2A	2Y
L	X	H
H	L	L
H	H	H

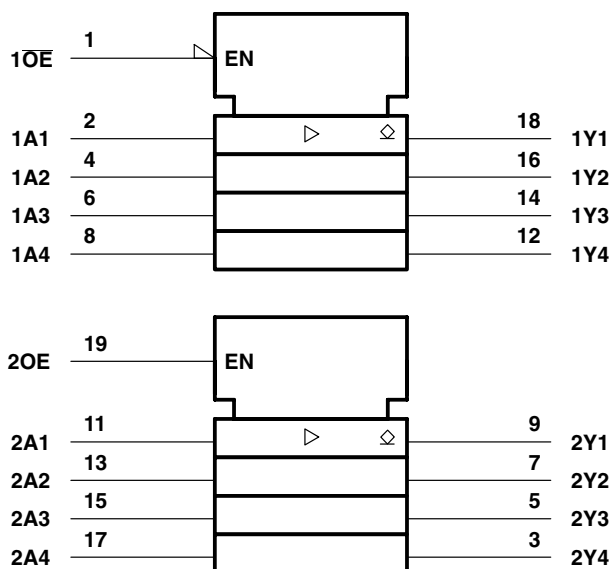
# SN74BCT757

## OCTAL BUFFER/DRIVER

### WITH OPEN-COLLECTOR OUTPUTS

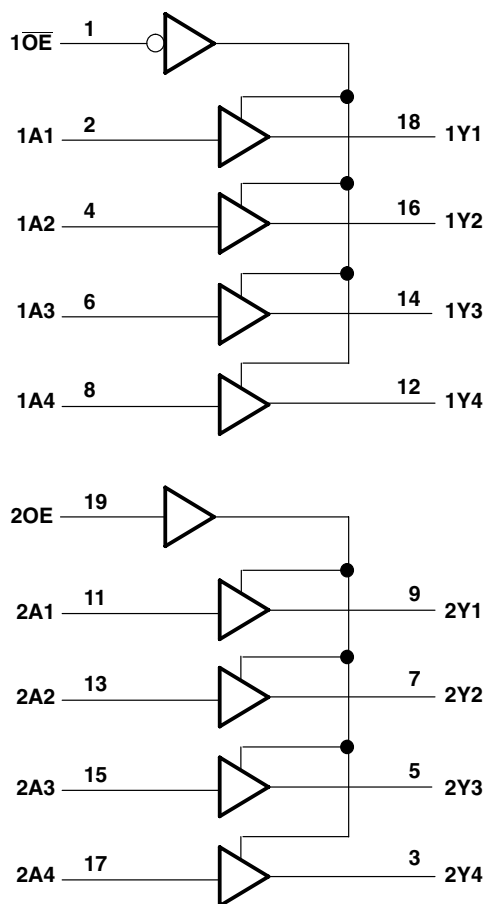
SCBS041D – NOVEMBER 1989 – REVISED NOVEMBER 1993

#### logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input voltage range, $V_I$	–0.5 V to 7 V
Input current range, $I_I$	–30 mA to 5 mA
Voltage range applied to any output in the disabled or power-off state, $V_O$	–0.5 V to 5.5 V
Voltage range applied to any output in the high state, $V_O$	–0.5 V to $V_{CC}$
Current into any output in the low state, $I_O$	128 mA
Operating free-air temperature range	0°C to 70°C
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

**recommended operating conditions (see Note 1)**

	MIN	NOM	MAX	UNIT
$V_{CC}$ Supply voltage	4.5	5	5.5	V
$V_{IH}$ High-level input voltage	2			V
$V_{IL}$ Low-level input voltage			0.8	V
$V_{OH}$ High-level output voltage			5.5	V
$I_{IK}$ Input clamp current			-18	mA
$I_{OL}$ Low-level output current			64	mA
$T_A$ Operating free-air temperature	0		70	°C

NOTE 1: Unused or floating inputs must be held high or low.

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ ,	$I_I = -18\text{ mA}$			-1.2	V
$V_{OL}$	$V_{CC} = 4.5\text{ V}$ ,	$I_{OL} = 64\text{ mA}$	0.42		0.55	V
$I_I$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 7\text{ V}$			0.1	mA
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 2.7\text{ V}$			20	μA
$I_{IL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 0.5\text{ V}$			-1	mA
$I_{OH}$	$V_{CC} = 4.5\text{ V}$ ,	$V_{OH} = 5.5\text{ V}$			0.1	mA
$I_{CC}$	$V_{CC} = 5.5\text{ V}$ ,	Outputs high			34	mA
		Outputs open			77	
		OE and $\overline{OE}$ inactive			10	
$C_i$	$V_{CC} = 5\text{ V}$ ,	$V_I = 2.5\text{ V}$ or $0.5\text{ V}$		6		pF
$C_o$	$V_{CC} = 5\text{ V}$ ,	$V_O = 2.5\text{ V}$ or $0.5\text{ V}$		4		pF

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

**switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50\text{ pF}$  (unless otherwise noted) (see Note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5\text{ V}$ , $T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
$t_{PLH}$	A	Y	6.9	8.3	9.6	6.6	10.1	ns
$t_{PHL}$			2.4	4.2	6	2	6.6	
$t_{PLH}$	2OE	Y	11	14.8	17.9	10.8	19.7	ns
$t_{PHL}$			2.9	4.6	6.2	2.6	6.9	
$t_{PLH}$	$1\overline{OE}$	Y	11.4	13.9	16.1	10	18	ns
$t_{PHL}$			4.4	6.1	7.8	4	8.5	

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN74BCT757DW</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT757
SN74BCT757DW.A	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT757
<a href="#">SN74BCT757N</a>	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74BCT757N
SN74BCT757N.A	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74BCT757N

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## TUBE



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74BCT757DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74BCT757DW.A	DW	SOIC	20	25	507	12.83	5080	6.6
SN74BCT757N	N	PDIP	20	20	506	13.97	11230	4.32
SN74BCT757N.A	N	PDIP	20	20	506	13.97	11230	4.32

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



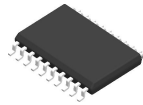
PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



14/18 Pin Only  
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



4220724/A 05/2016

## NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



# EXAMPLE BOARD LAYOUT

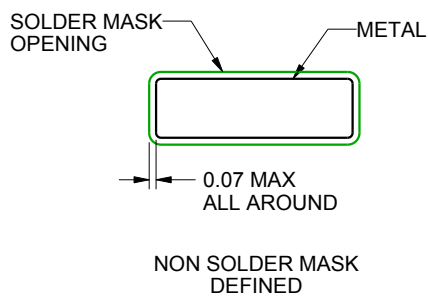
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2025, Texas Instruments Incorporated